



## **CERTIFICATE OF MAILING**

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ovember 30, 2004.

nkman, Reg. No. 40,532

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

Takagi et al.

Serial No.:

10/709,631

Filed:

May 18, 2004

Group Art Unit:

3635

Confirmation No.: 3630

Examiner:

Unknown

Title:

FORM PANEL FOR PLACING CONCRETE

Our Ref .:

SHG-029P2

Cincinnati, Ohio 45202

November 30, 2004

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

> SUBMISSION OF SUPPLEMENTAL DECLARATION. POWER OF ATTORNEY, AND PETITION AND REQUEST FOR CORRECTION OF FILING RECEIPT

Sir:

Applicants submit herewith a Supplemental Declaration, Power of Attorney, and Petition to correct the priority claim in the above-referenced application. It is requested that a corrected filing receipt be issued in the above-referenced application to include Applicants' corrected priority claim for foreign applications.

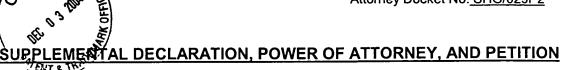
Applicants believe there is no fee due in connection with submission of the Supplemental Declaration, Power of Attorney, and Petition. In the event that a fee is due at this time, please charge Deposit Account No. 23-3000.

Respectfully submitted,

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As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

FORWIPANEL FOR PLACING CONCRETE				
the specification of which (check one below):				
( )	is attached hereto.			
( <b>X</b> )	was filed on May 18, 2004 as Application Serial No. 10/709,631 or Express Mail No, and was amended on (if applicable).			
( )	was filed on as PCT International Application No , and as amended under PCT Article 19 on (if any).			
	eby state that I have reviewed and understand the contents of the above tion, including the claims, as amended by any amendment referred to			
Trademark Office a	knowledge the duty to disclose to the United States Patent and all information known to me to be material to patentability as defined in ederal Regulations \$1.56			

§119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a

filing date before that of the application on which priority is claimed:

I hereby claim foreign priority benefits under Title 35, United States Code,

**Priority Claimed?** Prior Foreign Application(s) (X) Yes ( ) No 2001-360062 26/11/2001 Japan Day/Month/Year Filed (Number) (Country) 15/03/2002 (X) Yes ( ) No 2002-72643 <u>Japan</u> Day/Month/Year Filed (Country) (Number) 24/04/2002 (X) Yes ( ) No 2002-122286 Japan Day/Month/Year Filed (Number) (Country) 26/11/2002 (X) Yes ( ) No PCT/JP02/12321 Day/Month/Year Filed (Number) (Country)

I hereby claim the benefit under Title 35, United States Code, §120 and/or §119(e) of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(Serial No.)	(Filing Date)	(Status: Patented, Pending, or Abandoned)
(Serial No.)	(Filing Date)	(Status: Patented, Pending, or Abandoned)
(Serial No.)	(Filing Date)	(Status: Patented, Pending, or Abandoned)

I hereby appoint the practitioners associated with the customer number 26875, as my attorneys or agents, with full power of substitute and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Address all correspondence and telephone calls to

Thomas W. Flynn

Address of customer number 26875 Telephone (513) 241-2324

Wherefore I pray that Letters Patent be granted to me for the invention or discovery described and claimed in the foregoing specification and claims, and I hereby subscribe my name to the foregoing specification and claims, declaration, power of attorney, and this petition.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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